WAITRONY 慧創就

Micro Embedded Infrared Receiver Module

0-05-07-07 Preliminary

Module No.: PIC-8102ASE

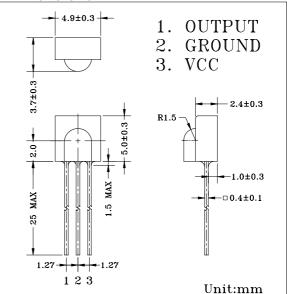
1. Features:

- > Microminiature size
- > Embedded protection
- ➤ Built-in exclusive IC
- Wide half angle & long reception distance
- Continuous Signal Acceptable
- ➤ Suitable for R-C oscillating transmitter
- ➤ High protection ability to EMI
- > Side view
- ➤ Wide voltage operating: 2.7V ~ 5.5V

2. Applications

- AV instruments (Audio, TV, VCR, CD player)
- Home appliances (Air-conditioner, Fan, Light.)
- Remote control for wireless devices

Dimensions



3. Absolute Maximum Ratings

(Ta=25°C)

2.110301000 1/10/11/11/11/15				
Parameter		Symbol	Ratings	Unit
Supply Voltage		Vcc /	6,0	V
Operating Tempera	iture	Topr	-10 ~ +60	°C
Storage Temperatur	re	Tstg	-20 ~ +75	°C /
Soldering Tempera	ture *1	Tsol	240	°C

^{*1} At the position of 2mm from the bottom of the package within 5 seconds.

4. Electro-optical Characteristics

(Ta=25°C)

1					`	,
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply Voltage	Vcc		2.7		5.5	V
Current Consumption	Icc	Input Signal = 0		1.0	1.5	mA
Reception Distance	d	200±5Lux, Vcc=3.0V	7	10		m
Half Angle (Horizontal)	$\Delta \theta h$			±45		deg
Half Angle (Vertical)	$\Delta \theta v$			+45/-40		deg
B.P.F. Center Frequency	Fo			37.9		kHz
Peak Wavelength	λр			940		nm
Signal Output	So		Active Low			
High Level Output Voltage	Voh		Vcc-0.5			V
Low Level Output Voltage	Vol			0.2	0.4	V
High Level Pulse Width	Twh	Burst Wave = 600µs	500	600	700	μs
Low Level Pulse Width	Twl	burst wave = 600μs	500	600	700	μs

5. Reliability Test Items

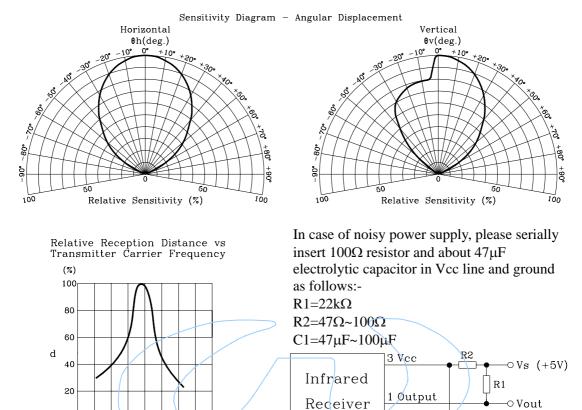
(Ta=25°C)

J. Remadility Test Items		(1a-25 C)
Test Items	Test Conditions	Ratings
High Temperature Storage	Ta=60°C, Vcc=3.0V	t=240hr.
Low Temperature Storage	Ta=-10°C, Vcc=3.0V	t=240hr.
High Temperature High Humid Storage	Ta=40°C, 90%RH, Vcc=3.0V	t=240hr.
Temperature Cycling	-20°C (30min) ~ +70°C (30min)	20 cycles
Soldering Heat	240±5°C	5 sec.

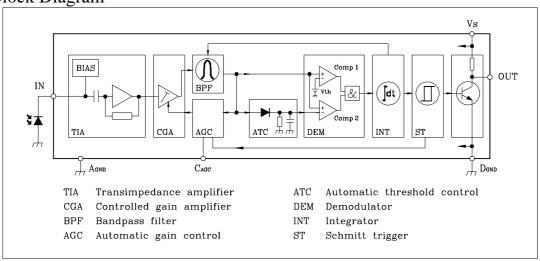


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Module No.: PIC-8102ASE



Block Diagram



Module

C1

-○ Ground

2 Ground

Standard Inspection

Among electrical characteristics, total quantity will be inspected as below:-

• Distance between emitter and detector

10 20 30 40 50 60 70 80 (kHz)

fo

- Current consumption
- H level output voltage
- ⊙ L level output voltage



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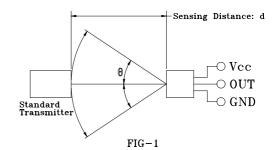
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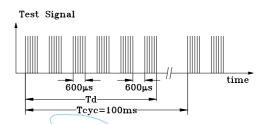
Testing Method

Distance between emitter and detector specifies maximum distance that output waveform satisfies the standard (FIG-3) under the conditions below against the standard transmitter.

- a. Measuring place Indoor without extreme reflection of light.
- b. Ambient light source
 Detecting surface illumination is 200±5Lux
 under ordinary white fluorescence lamp of
 no high frequency lightning.
- c. Standard transmitter

 Transmitter wave indicated in FIG-2 of standard transmitter is arranged to satisfy Vo≥50mVp-p under the measuring circuit specified in FIG-3





Tcyc-Td>25ms is recommended for optimal function

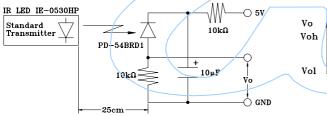
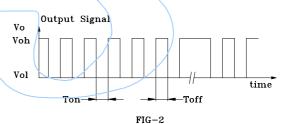
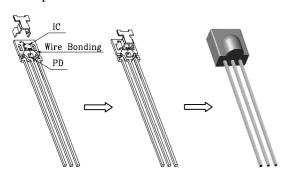


FIG-3 Power Output Measurement Circuit



Embedded Design

This design (Fig-4) is to install a metal case on the carrier lead frame to cover the semiconductor components, in order to shield it electromagnetically within the epoxy resin encapsulation.



Die Bonding Embedded Cover After
Protection Encapsulation

FIG-4 Embedded Design

Precautions for Use

- a. Store and use where there is no force causing transformation or change in quality.
- b. Store and use where there is no corrosive gas or sea (salt) breeze.
- c. Store and use where there is no extreme humidity.
- d. Solder the lead pin within the condition of ratings. After soldering, do not add exterior force.
- e. Do not wash this device. Wipe the stains of diode side with a soft cloth. You can use the solvent, ethyl alcohol, or methyl alcohol only.
- f. To prevent static electricity damage to the pre-amp, make sure that the human body, the soldering iron are connected to ground before using.